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Docket No.

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Application No.

10/824,754

## INFORMATION DISCLOSURE CITATION

## in an Application

(Use several sheets if necessary)

Applicant

Dung-Ching Perng

Filing Date

April 15, 2004

Group Art Unit

2812

## U.S. PATENT DOCUMENTS

Examiner Initial	Ref. No.	Document Number	Date of Patent	Name	Class	Subclass	Filing Date if Appropriate
POW	A1	5,874,355	2/23/99	Huang et al.			
	A2	5,969,422	10/19/99	Ting et al.			
	A3	6,217,721	4/17/01	Xu et al.			
	A4	6,294,836	9/25/01	Paranjpe et al.			
	A5	6,362,099	3/16/02	Gandikota et al.			
	A6	6,444,567	9/3/02	Besser et al.			
	A7	6,455,424	9/24/02	McTeer et al.			
	A8	6,468,906	10/22/02	Chan et al.			
	A9	6,495,200	12/17/02	Chan et al.			
	A10	6,635,964	10/21/03	Maex et al.			
	A11	6,664,187	12/16/03	Ngo et al.			
	A12	6,703,307	3/9/04	Lopatin et al.			

## U.S. PATENT APPLICATION PUBLICATION DOCUMENTS

Examiner Initial	Ref. No.	Document Number	Date of Publication	Name	Class	Subclass	Filing Date if Appropriate
POW	A13	2002/0187632	12/12/02	Marsh			
POW	A14	2003/0203617	10/30/03	Lane et al.			

## FOREIGN PATENT DOCUMENTS

Examiner Initial	Ref. No.	Document Number	Date of Publication	Country	Class	Subclass	Translation	
							Yes	No
	B1							
	B2							
	B3							

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages etc.)

POW	C1	Itabashi Takeyuki et al., <i>Electroless Deposited CoWB for Copper Diffusion Barrier Metal</i> , 2002 International Interconnect Technology Conference, pp. 285-287.						
POW	C2	Zylberman et al., <i>Comparative Study of Electroless Co(W,P) and Co(Mo,P) Thin-Films for Capping and Barrier Layers for Cu Metallization</i> , 2002 Advanced Metallization Conference, 2 pgs.						

EXAMINER

DATE CONSIDERED

4/18/05

EXAMINER: Initial if references considered, whether or not citation is in conformance with MPÉP § 609; Draw line through citation if not in conformance and not considered.  
Include copy of this form with next communication to applicant.